



**ASIC-Based MXM**  
**AI-MXM-H84A**



# Accelerating Smart Traffic Monitoring by Multitasking Inference Data

Edge AI computing systems powered by ASIC are poised to become the devices of choice for specific AI applications, such as neural network (NN) and deep learning (DL) acceleration. Aetina provides a comprehensive ASIC-based product line to benefit the high efficiency and low latency to accelerate edge AI operational processing.

Aetina **AI-MXM-H84A** is the world's first MXM 3.1 module powered by four high-efficiency Hailo-8™ AI inference processors, driving up to 104 TOPS AI performance with unprecedented energy efficiency. The AI-MXM-H84A optimizes in size, weight, and power (SWaP), along with Aetina's customization services, industrial-grade mechanism, and integration of AI inference models, making it an ideal module for various embedded industrial devices. Meanwhile, developers can leverage Hailo's state-of-the-art software package and AI developer tools to power various AI and edge computing applications, reduce compute-intensive workloads, and accelerate AI inference at the edge.

## Feature Highlights

- **Powerful AI Inference Processor**  
Chip-down with 4x Hailo-8 AI processors
- **Dedicated Fine-Tune Services**  
AI inference model integration for ASIC-based hardware
- **Out-of-Box Performance**  
Up to 104 TOPS AI performance
- **Comprehensive SW Tools**  
Mature SW package and AI developer tools
- **Best-in-Class Power Efficiency**  
Typical power consumption just at 25W
- **Robust and Industrial-grade Design**  
Industry MXM 3.1 Type B form factor

# Powerful and Flexible to Support Various Markets & Applications



Automotive



Smart City



Smart Building



Smart Retail



Smart Factory

## Specification

Model Number	AI-MXM-H84A
Engine Specs	4x Hailo-8 AI processor with up to 26 TOPS and best-in-class power efficiency
AI Performance	104 TOPS
Memory Specs	N/A
Feature Support	PCI Express 3.0 x16 Supported TensorFlow and ONNX
Display	N/A
Power Consumption	25 W (Typical power consumption)
Form Factor	MXM graphics module version 3.1, Type B
Dimensions (WxD)	82.0 x 105.0 mm (3.22" x 4.13")
Net Weight	0.05 kg (0.1102 lb)
Vibration	2.4Grms @5~500 Hz, Sine, 0.5Hr/axis
Temperature	Standard: Operating Temp. :0 to + 70°C (32°F ~158°F )/ Storage Temperature: -40 to + 85°C (-40°F ~ 185°F)
Humidity	90% @ 40°C Related Humidity, Non-condensing
OS Support	Windows 10/11 64-bit Linux 64-bit
Certification	CE, FCC

\* Product Specifications are subject to change without prior notice